

规格书编号

SPEC NO: HDF977C3S4SP01

产品规格书

SPECIFICATION

CUSTOMER 客户: _____

PRODUCT 产品: _____ SAW FILTER _____

MODEL NO 型号: _____ HDF977C3-S4 _____

MARKING 印字: _____ 977 _____

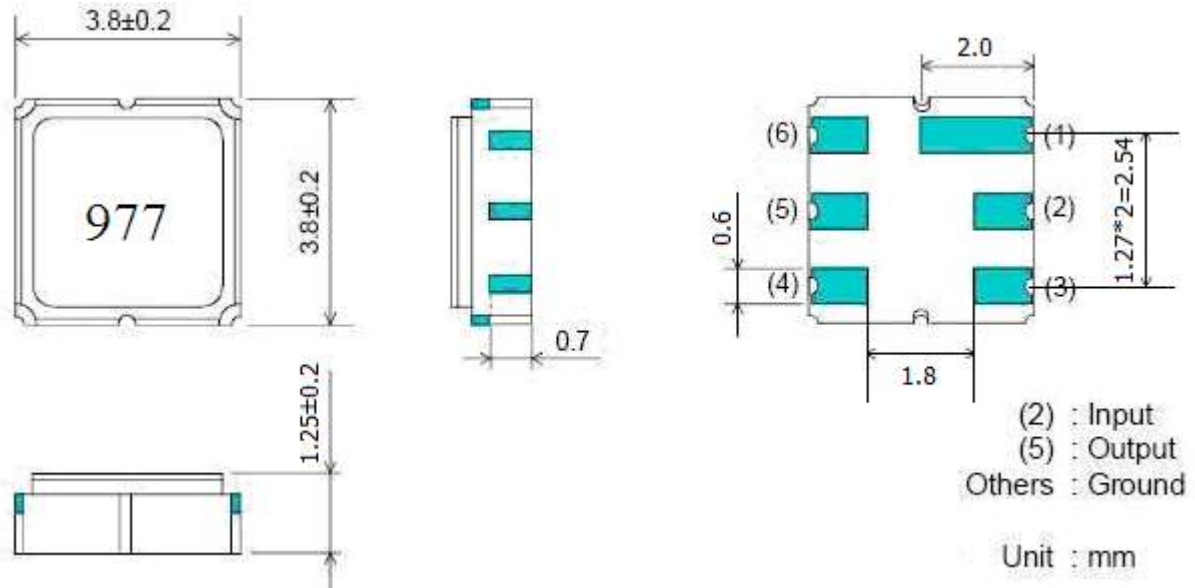
PREPARED 编制: _____ CHECKED 审核: _____

APPROVED 批准: _____ D A T E 日期: _____ 2014-10-8 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension



2. Maximum Rating

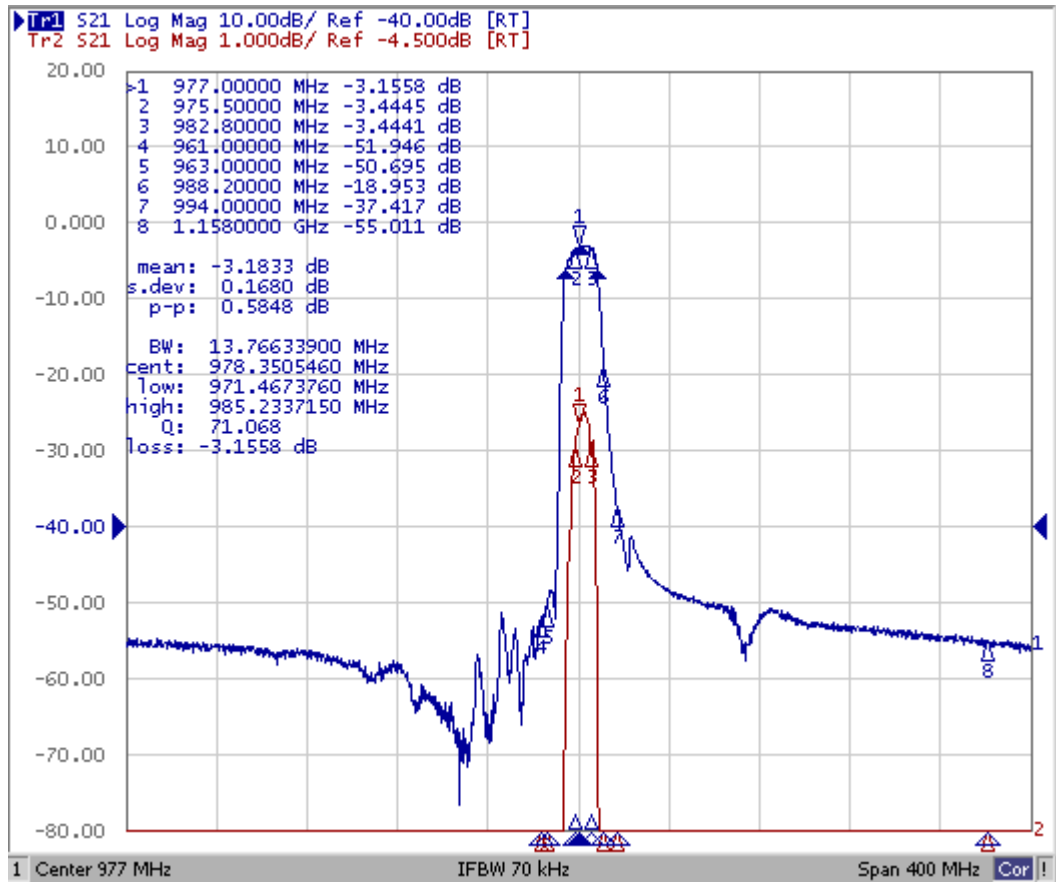
Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
DC. Voltage	10 V max.

3.1 Electronic Characteristics

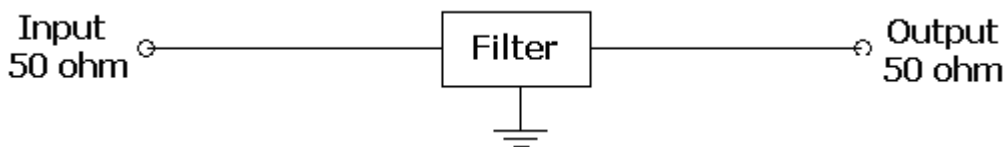
AT 25°C

	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	977	-
Insertion Loss (975.5~982.8 MHz)	dB		3.2	3.5
Amplitude Ripple (975.5~982.8 MHz)	dB		0.6	1.5
VSWR(975.5~982.8 MHz)			1.6	2.2
Absolute attenuation:				
961MHz	dB	20	22	-
963MHz		12	15	
988.2MHz		8.8	15	
994-1010MHz		34	38	
1158 MHz		47	55	
Input/Output Impedance	Ohms		50	

3.2 Frequency Characteristics



4. Test Circuit



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.1.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.1.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.1.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.1.

5-5 Solderability

Subject the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 3.1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.